

XP-002088740

1/1 - (C) WPI / DERWENT
AN - 85-089577 q15!
AP - JP830145665 830811
PR - JP830145665 830811
TI - Adhering polymer film to frame - by bonding to
substrate polymer, adhering assembly to frame and
dissolving substrate with suitable solvent
IW - ADHERE POLYMER FILM FRAME BOND SUBSTRATE POLYMER ADHERE
ASSEMBLE FRAME DISSOLVE SUBSTRATE SUIT SOLVENT
PA - (ASAH) ASahi CHEM IND CO LTD
PN - JP60038130 A 850227 DW8515 005pp
ORD - 1985-02-27
IC - B01D13/00 ; B29C65/52
FS - CPI
DC - A35
AB - J60038130 Prodn. comprises bonding a polymer film to a
substrate of different polymer material, adhering the
film to a frame, and dissolving the substrate away with
a solvent which can dissolve it but not the film.
- The polymer film is of e.g. nitrocellulose, PMMA,
vinylidenefluoride-tetrafluoroethylene copolymer,
polymethyl siloxane, polyacrylonitrile, PVA, PVC or PS.
- ADVANTAGE - Polymer film (for e.g. sepg., supporting,
or protecting material) is adhered easily and
continuously to a frame without warpages or tears, even
though it may be extremely thin (e.g. 5 microns or
less).(0/0)